# S<sub>0</sub>-like SAW Mode Resonator Based on LiTaO<sub>3</sub>/SiO<sub>2</sub>/SiC Platform

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### 1. Introduction

Recently, attention is paid to the S<sub>0</sub>-like SAW mode propagating on a LiNbO<sub>3</sub> (LN) thin plate bonded with the SiC supporting substrate<sup>1)-4)</sup>. The authors also studied the configuration, and pointed out that insertion of SiO<sub>2</sub> between LN and SiC layers is effective to enhance the electromechanical coupling factor  $k_{\rm eff}^2$  significantly with little reduction of the phase velocity.<sup>5),6)</sup>

This paper discusses application of LiTaO<sub>3</sub> (LT) to the S<sub>0</sub>-like SAW mode resonator instead of LN for improvement of the temperature stability in trade-off with  $k_{\text{eff}}^2$  reduction.

## 2. Structural Design

Since LT possesses the same crystallographic symmetry, we can use the structural design procedure<sup>5),6)</sup> established for the LN-based  $S_0$ -like SAW device.

**Fig. 1** shows variation of  $k_{\text{eff}}^2$  for the S<sub>0</sub> and SH<sub>0</sub> modes on the LT thin plate as a function of the rotation angle  $\alpha$ , i.e., for the Euler angle of  $[\alpha, -90^\circ, 90^\circ]$ . In this calculation, the LT thickness  $h_{\text{LT}}$  is set at 0.1 wavelength. When  $\alpha$  is 28°,  $k_{\text{eff}}^2$  of the S<sub>0</sub> Lamb mode reaches its maximum value of 11.62% while  $k_{\text{eff}}^2$  of the SH<sub>0</sub> mode is small (1.9%). Although  $\alpha$  is fixed at 28° in the following calculation, good S<sub>0</sub> mode suppression is possible by setting a close to 45° with certain reduction of  $k_{\text{eff}}^2$ .



Fig. 1 Variation of  $k_{\text{eff}}^2$  of S<sub>0</sub> and SH<sub>0</sub> on LT plate ( $h_{\text{LT}}$ =0.1 wavelength) with  $\alpha$ .

Next, the analysis is extended to the case where this LT plate is bonded on the SiC wafer with  $SiO_2$ 

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interposer. In the following analysis, IDT metallization ratio is fixed at 0.45.

**Fig. 2** shows the variation of  $k_{eff}^2$  and the phase velocity  $V_p$  with the SiO<sub>2</sub> thickness  $h_{SiO2}$  when  $h_{LT}=0.16p_I$ , where  $p_I$  is the IDT period. In this calculation, Al IDT thickness  $h_{Al}$  is set at  $0.04p_I$ . Although  $k_{eff}^2$  is significantly smaller than the value given in Fig. 1,  $k_{eff}^2$  increases rapidly with  $h_{SiO2}$  and mostly saturates to 8.3% with small  $h_{SiO2}$ . This is because soft and light SiO<sub>2</sub> isolates the LT plate from the stiff SiC substrate. As a tradeoff, decreases with  $h_{SiO2}$  in some extent.



Fig. 2 Variation of  $k_{\text{eff}}^2$  and  $V_{\text{p}}$  with  $h_{\text{SiO2}}$ .

Note that  $k_{\text{eff}}^2$  is also dependent on  $h_{\text{LT}}$  in addition to  $h_{\text{SiO2}}$ . **Fig. 3** shows variation of  $k_{\text{eff}}^2$  with  $h_{\text{LT}}$  and  $h_{\text{SiO2}}$  when  $h_{\text{Al}}=0.04p_{\text{I}}$ . It is seen that  $k_{\text{eff}}^2$  takes a maximum value of 8.3% when  $h_{\text{LT}}=0.16p_{\text{I}}$  and  $h_{\text{SiO2}}=0.15p_{\text{I}}$  and does not change rapidly with both  $h_{\text{LT}}$  and  $h_{\text{SiO2}}$  near the optimal point.



Fig. 3 Variation of  $k_{\text{eff}}^2$  with  $h_{\text{LT}}$  and  $h_{\text{SiO2}}$ .

**Fig. 4** shows the variation of  $k_{\text{eff}}^2$  and  $V_p$  with  $h_{\text{AI}}$  when  $h_{\text{LT}}=0.16p_1$  and  $h_{\text{SiO2}}=0.15p_1$ . Like the S<sub>0</sub>-like SAW mode resonators on LN, electrode mass-loading gives negative impacts. With an increase in  $h_{\text{AI}}$ ,  $k_{\text{eff}}^2$  increases a little and then decreases rapidly. In contrast,  $V_p$  decreases monotonically with  $h_{\text{AI}}$ . When another heavy material like Cu is chosen for the IDT,  $k_{\text{eff}}^2$  decreases more rapidly with  $h_{\text{AI}}$ . Since certain electrode thickness is necessary to make the electrode resistance small, use of Al is the best for this application.



Fig. 4 Variation of variation of  $k_{\text{eff}}^2$  and  $V_{\text{p}}$  with  $h_{\text{Al}}$ .

**Fig. 5** shows variation of temperature coefficient of velocity (TCV) with  $h_{SiO2}$  when  $h_{LT}=0.16p_1$  and  $h_{Al}=0.04p_I$ . TCV increases rapidly with  $h_{SiO2}$  and almost saturates when  $h_{SiO2}=0.04p_I$ . temperature coefficient of frequency (TCF) seems quite possible when the thermal expansion coefficient toward the propagation direction of this composite structure.



Fig. 5 Variation of TCV of  $S_0$ -like mode SAW resonator using LT with  $h_{SiO2}$  when  $h_{LT}=0.16p_1$ . For comparison, that of the  $S_0$ -like SAW resonator using LN is also shown.

This means zero TCF, relatively large  $k_{\text{eff}}^2$ , and high  $V_{\text{p}}$  are achievable simultaneously in this configuration.

In the figure, TCV of S<sub>0</sub>-like mode SAW resonator on LN<sup>5)</sup> is also shown. Although use of LT gives smaller  $k_{eff}^2$  than that of LN, good TCV makes use of LT attractive.

## 3. Admittance characteristics

**Fig. 6** shows the admittance *Y* and conductance *G* when  $p_1$ =6 µm obtained by the periodic 2D FEM analysis. The main response is seen at around 1 GHz. The cutoff of bulk radiation is circa 1.4 GHz, which is determined by the slow-shear wave velocity in SiC.

Two spurious resonances are seen below the main resonances, and those at 0.5 GHz and 0.6 GHz are due to Rayleigh and SH<sub>0</sub>-like SAW modes respectively. These resonances may be suppressed by finely adjusting  $\theta$  and/or  $h_{\text{LT}}$ .



Fig. 6 Calculated |Y| and G of designed S<sub>0</sub>-like SAW resonator.

## 6. Conclusion

This paper described the S<sub>0</sub>-like SAW mode resonator using the Al-eletrode/LT/SiO<sub>2</sub>/SiC structure. It was shown that zero TCF, relatively large  $k_{\text{eff}}^2$ , and high  $V_p$  are achievable simultaneously in this configuration.

As the next step, the authors will apply the piston mode design to suppression transverse mode resonances.

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